

N-Channel 20 V (D-S) MOSFET with Schottky Diode

MOSFET PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
20	0.125 at $V_{GS} = 4.5$ V	2.4
	0.200 at $V_{GS} = 2.5$ V	1.8

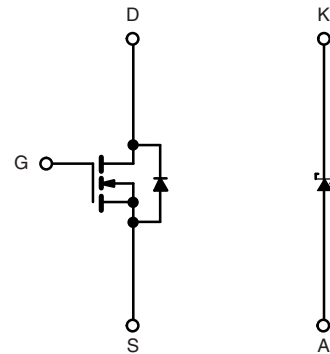
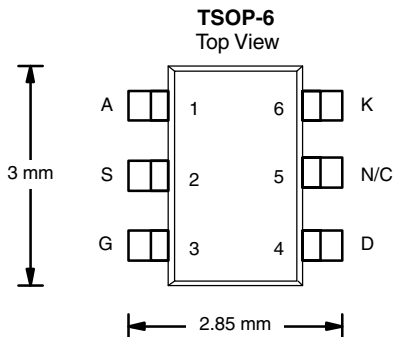
SCHOTTKY PRODUCT SUMMARY		
V_{KA} (V)	V_F (V) Diode Forward Voltage	I_F (A)
20	0.48 V at 0.5 A	0.5

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- LITTLE FOOT® Plus
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE



Ordering Information: Si3812DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)					
Parameter	Symbol	5 s	Steady State	Unit	
Drain-Source Voltage (MOSFET)	V_{DS}	20		V	
Reverse Voltage (Schottky)	V_{KA}	20		V	
Gate-Source Voltage (MOSFET)	V_{GS}	± 12		V	
Continuous Drain Current ($T_J = 150$ °C) (MOSFET) ^a	I_D	$T_A = 25$ °C	2.4	2.0	A
		$T_A = 85$ °C	1.7	1.4	
Pulsed Drain Current (MOSFET)	I_{DM}	8		A	
Continuous Source Current (MOSFET Diode Conduction) ^a	I_S	1.05	0.75		
Average Forward Current (Schottky)	I_F	0.5	0.5		
Pulsed Forward Current (Schottky)	I_{FM}	8	8		
Maximum Power Dissipation (MOSFET) ^a	P_D	$T_A = 25$ °C	1.15	0.83	W
		$T_A = 85$ °C	0.59	0.53	
Maximum Power Dissipation (Schottky) ^a	P_D	$T_A = 25$ °C	1.0	0.76	
		$T_A = 85$ °C	0.52	0.48	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		°C	

Note:

a. Surface mounted on 1" x 1" FR4 board.

THERMAL RESISTANCE RATINGS						
Parameter		Device	Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^a	$t \leq 5$ s	MOSFET	R_{thJA}	93	110	°C/W
		Schottky		103	125	
	Steady State	MOSFET		130	150	
		Schottky		140	165	
Junction to Foot (MOSFET Drain, Schottky Cathode)	Steady State	MOSFET	R_{thJF}	75	90	
		Schottky		80	95	

Note:

a. Surface mounted on 1" x 1" FR4 board.

MOSFET AND SCHOTTKY SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0$ V, $V_{GS} = \pm 12$ V			± 100	nA
Zero Gate Voltage Drain Current (MOSFET and Schottky)	I_{DSS}	$V_{DS} = 16$ V, $V_{GS} = 0$ V			1	μA
		$V_{DS} = 16$ V, $V_{GS} = 0$ V, $T_J = 85$ °C			10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5$ V, $V_{GS} = 4.5$ V	5			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5$ V, $I_D = 2.4$ A		0.100	0.125	Ω
		$V_{GS} = 2.5$ V, $I_D = 1.0$ A		0.160	0.200	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 5$ V, $I_D = 2.4$ A		5		S
Schottky Diode Forward Voltage ^a	V_{SD}	$I_S = 1.5$ A, $V_{GS} = 0$ V		0.79	1.1	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 10$ V, $V_{GS} = 4.5$ V, $I_D = 2.4$ A		2.1	4.0	nC
Gate-Source Charge	Q_{gs}			0.3		
Gate-Drain Charge	Q_{gd}			0.4		
Gate Resistance	R_g		1		3.7	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10$ V, $R_L = 10 \Omega$ $I_D = 1$ A, $V_{GEN} = 4.5$ V, $R_g = 6 \Omega$		10	17	ns
Rise Time	t_r			30	50	
Turn-Off Delay Time	$t_{d(off)}$			14	25	
Fall Time	t_f			6	12	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 3.0$ A, $di/dt = 100$ A/ μs		30	50	

Notes:

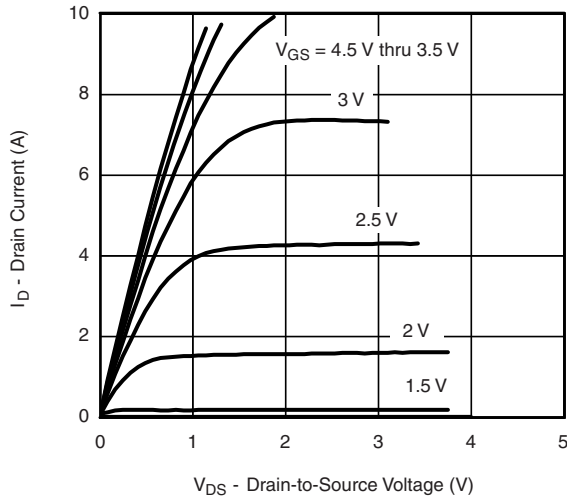
a. Pulse test; pulse width $\leq 300 \mu s$, duty cycle ≤ 2 %.

b. Guaranteed by design, not subject to production testing.

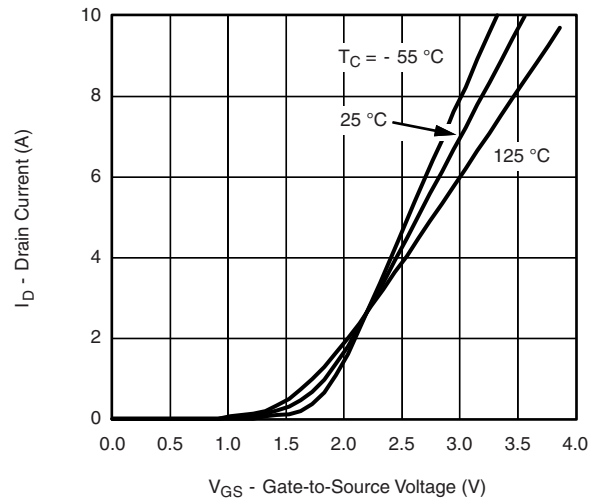
SCHOTTKY SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Forward Voltage Drop	V_F	$I_F = 0.5$ A		0.42	0.48	V
		$I_F = 0.5$ A, $T_J = 125$ °C		0.33	0.4	
Maximum Reverse Leakage Current	I_{rm}	$V_R = 20$		0.002	0.100	mA
		$V_R = 20$ V, $T_J = 75$ °C		0.06	1	
		$V_R = 20$ V, $T_J = 125$ °C		1.5	10	
Junction Capacitance	C_T	$V_R = 10$ V		31		pF

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

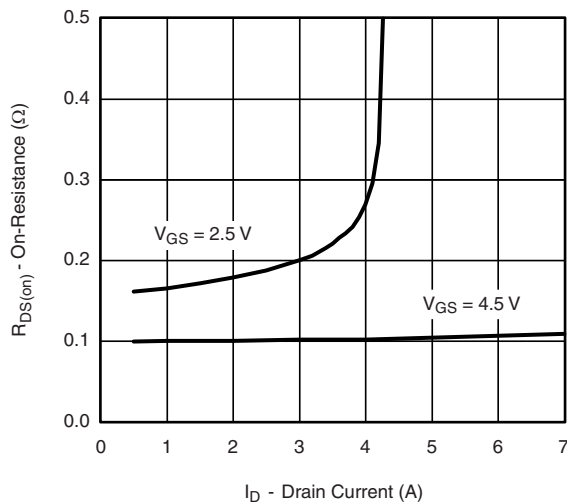
MOSFET TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



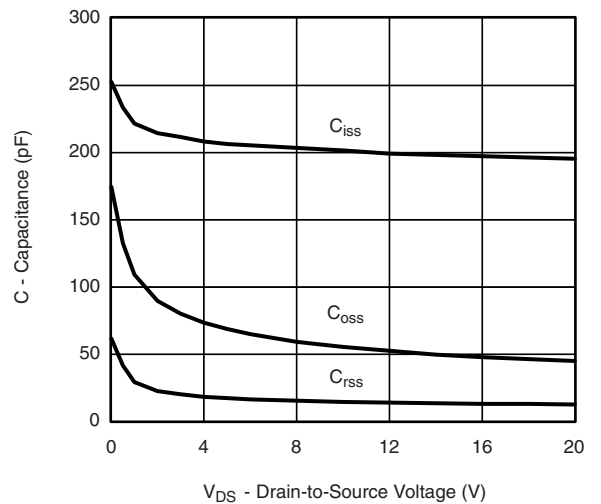
Output Characteristics



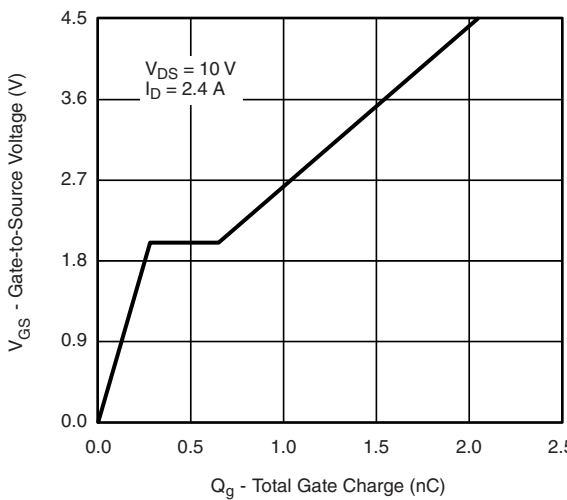
Transfer Characteristics



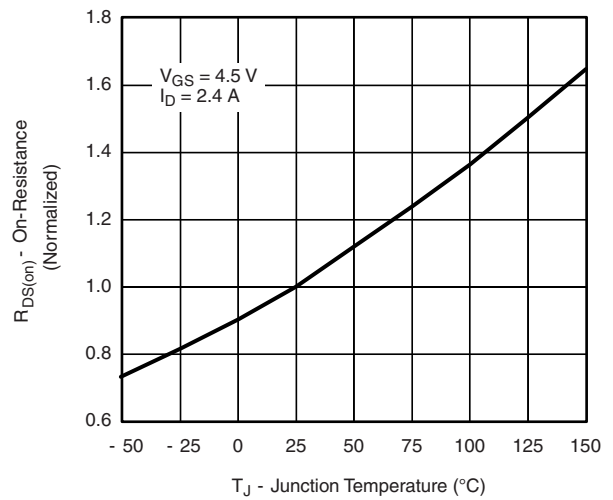
On-Resistance vs. Drain Current



Capacitance

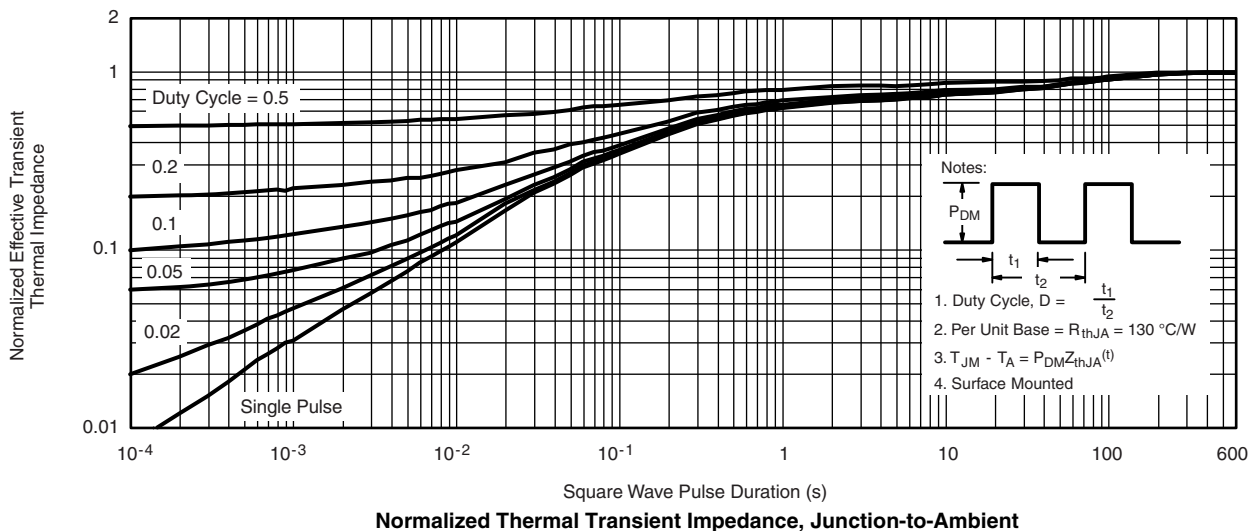
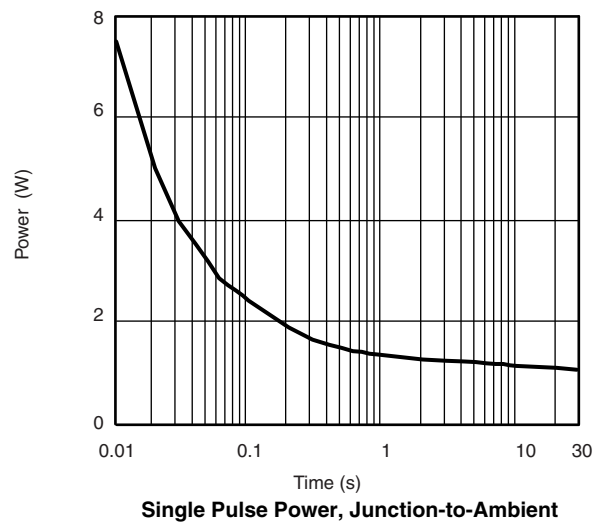
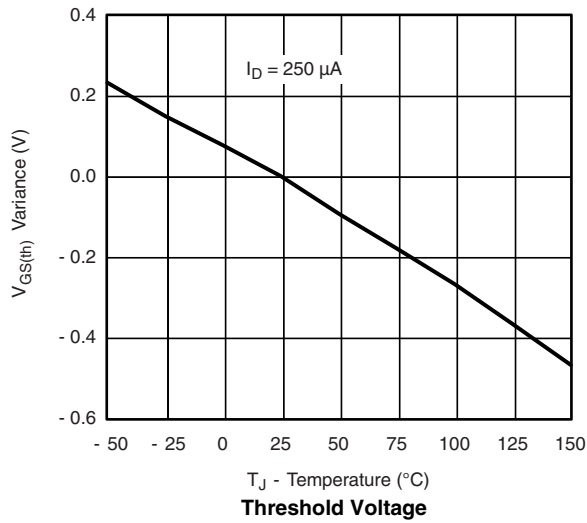
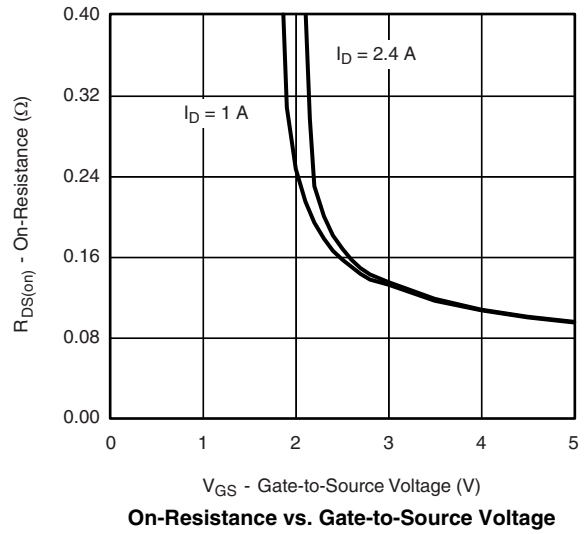
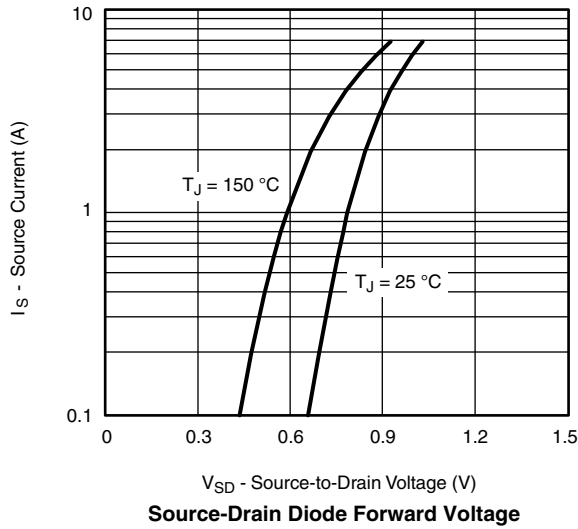


Gate Charge

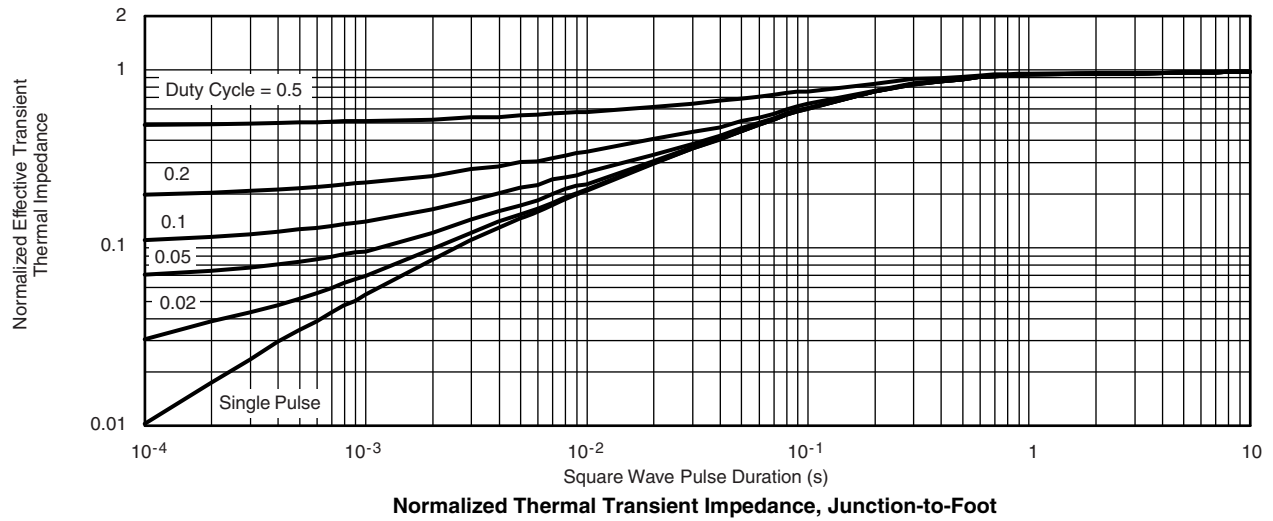


On-Resistance vs. Junction Temperature

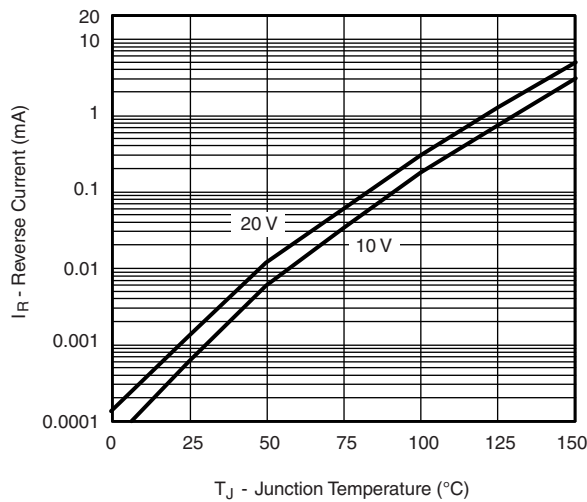
MOSFET TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



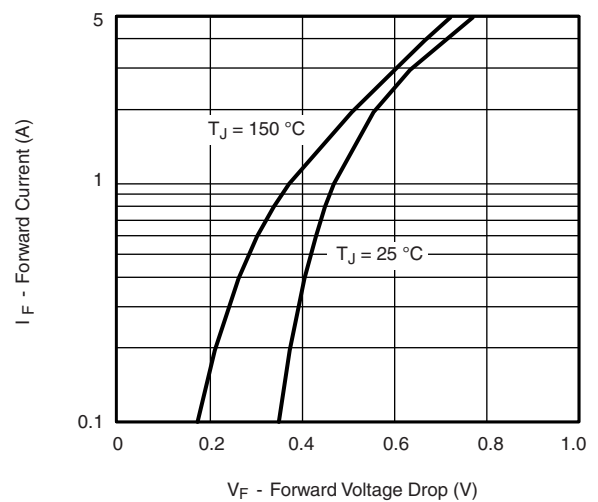
MOSFET TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



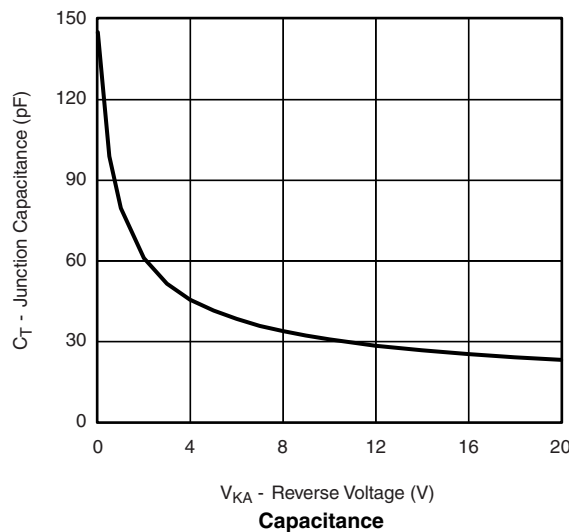
SCHOTTKY TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



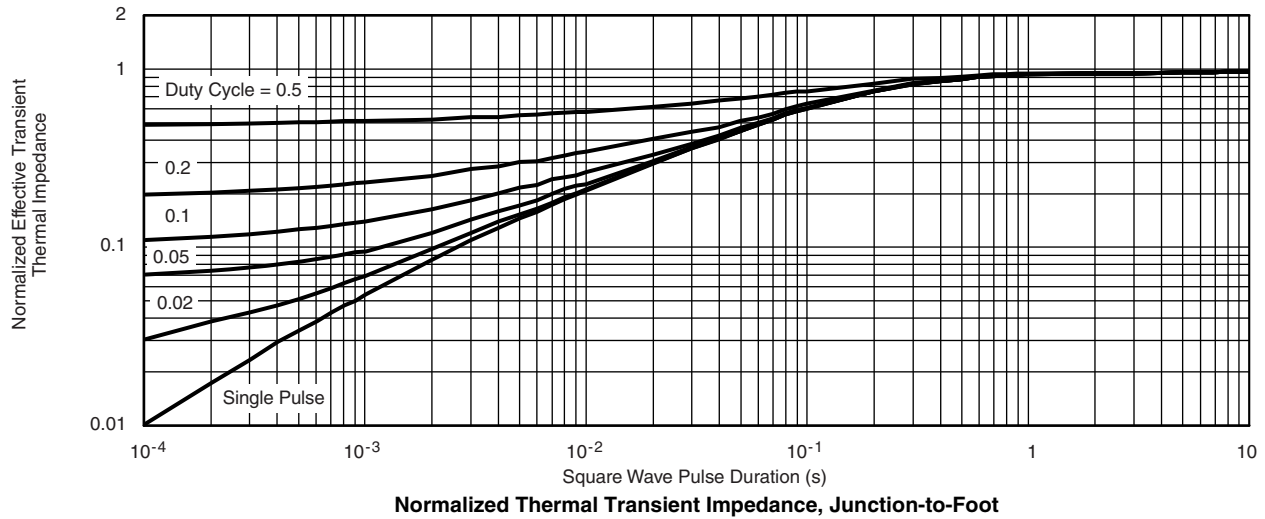
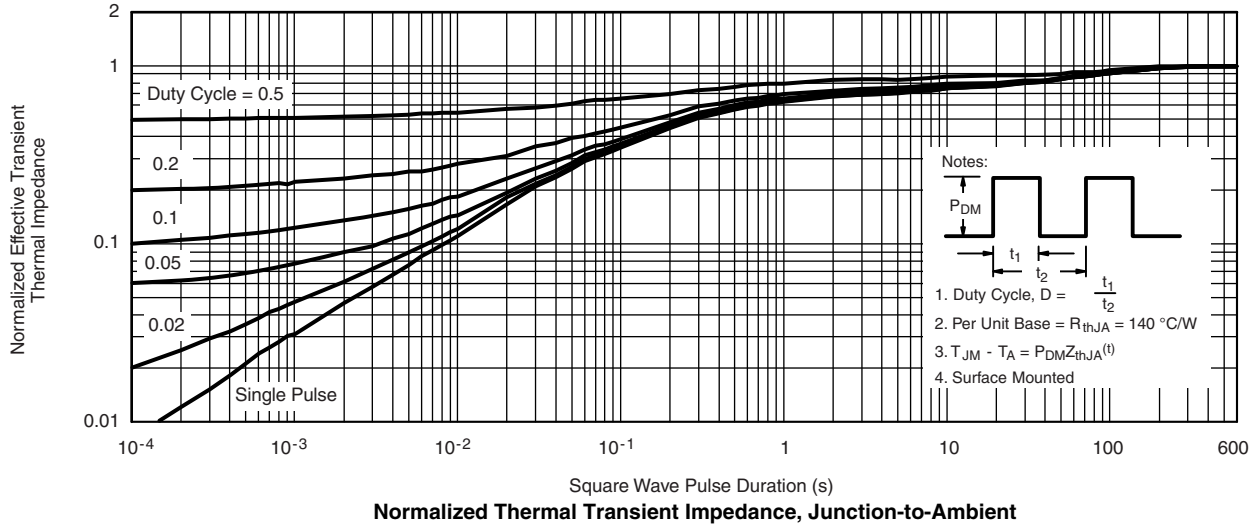
Reverse Current vs. Junction Temperature



Forward Voltage Drop



SCHOTTKY TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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